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Boost Electrification and Digitalization market with ST's NEV CC total solution

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NEV Competence Center & PTS BU | Marketing



What we did in the past

Benchmarking

- Automotive market was dominated by global Tier 1 customers.
- Silicon design was led by global Tier 1 customers in all traditional Body, Powertrain, safety and Chassis applications.
- Local tier 1 benchmark global Tier 1 system design and use same silicon solutions.



Door zone



Lighting



Braking



Airbag

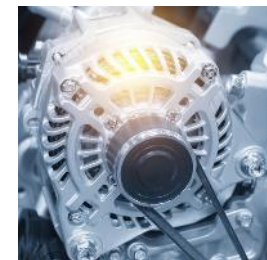
2005 to 2010

WW standard

- Local Tier 1 customers competence is stronger and stronger, especially in engine management market and Alternator regulator market.
- Co-developed dedicated local devices L9177A, L9779, L9788 U-chip CN6 compliance EMS Solution.
- Co-developed dedicated local AR devices L9916, L9918



Motorcycle

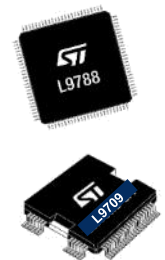


AR



EMS

2011 to 2018



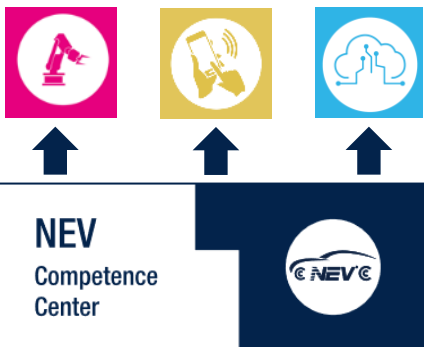
Fast evolution of automotive market

New Customers database

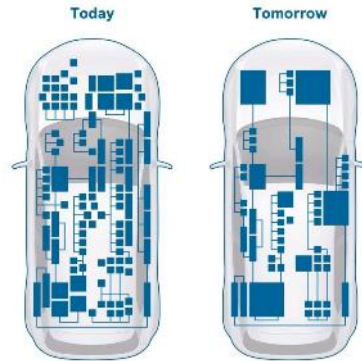
Before: Traditional global Tier 1 (Bosch Conti)

Now: Car makers, traditional local tier1, Industrial players, Mobile phone players, IoT players

Bigger customer data base with different design concept and various technical requirement.



New system architecture



New system architecture required new product proposal, new system proposal and new knowhow to support this new market

Software Defined Vehicle (SDV)

Software is the core enabler for key automotive innovations in connectivity, autonomous driving, electrification and thus increasingly becomes a differentiating factor



Faster than traditional Tier 1

Lead market trend:

Fast market evolution with more advanced requirement than the W.W.



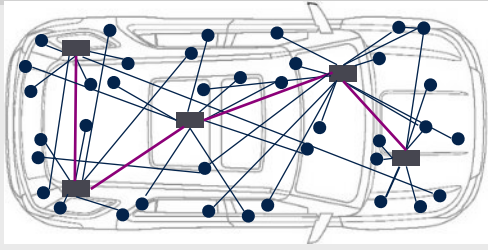
Shorter design cycle:

New devices design cycle requirement is 1.5 Years, required NEV CC deeply involved in SPEC definition, silicon validation and system validation

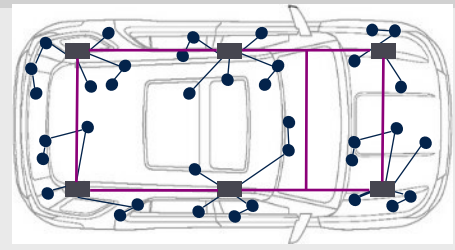


Creation of NEV CC and Team Mission

Domain



Zone



Keep leading position on
all conventional domain &
Expand our footprint in new automotive
market trends

(*E*lectrification, *D*igitalization)

New architecture trend

(*D*omain, *Z*one)

Through...

- **NSP** (New Solution Proposal) helping shorten customer development cycle.
- **NPP** (New Product Proposal) development targeting local customer needs.

Leading position on traditional domain



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ST: 全球多元化汽车半导体领导者 超过30年的经验

2019

37% of ST revenue 市场份额 (on SAM) >10%

>\$3.61B

2018

+1.5% Y-o-Y

\$3.55B
ADG 营业额



覆盖所有汽车应用



Powertrain for ICE



Body & Convenience



Chassis and Safety



Electro-mobility



ADAS



Mobility Service

#1



发动机控制



24 GHz
毫米波
雷达



ADAS
Safety



车载互联



Car Audio
功率放大
器



GNSS
全球卫
星定位
系统



智能
功率
器件



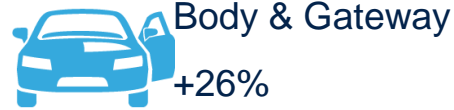
SiC

ST引领汽车应用市场

ADG leading automotive gateway market secure MCU for in-vehicle networking & FOTA

1st Automotive Gateway supplier

FY'19 Driven by:

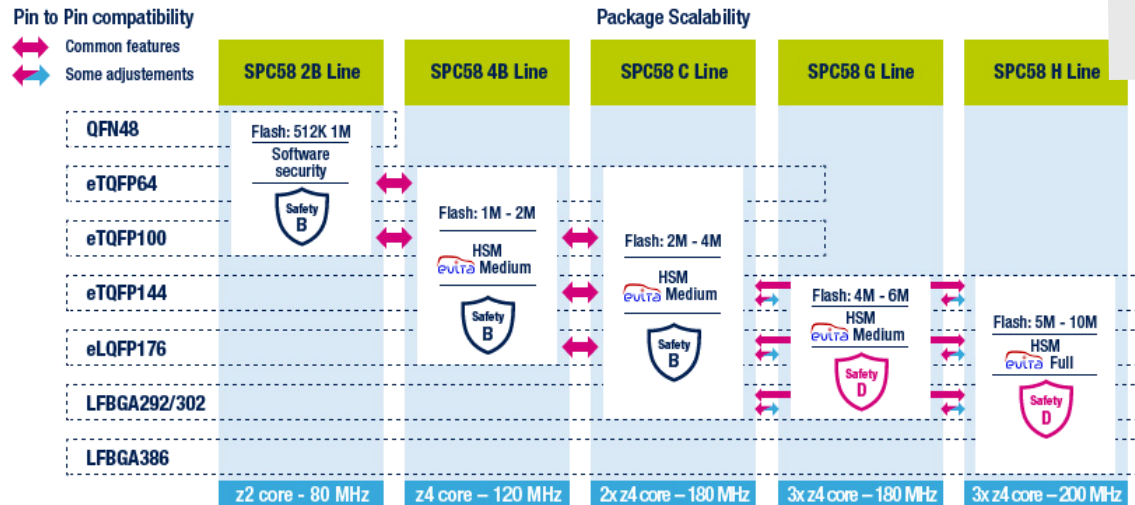


Automotive MCU FY'19 Revenue Growth

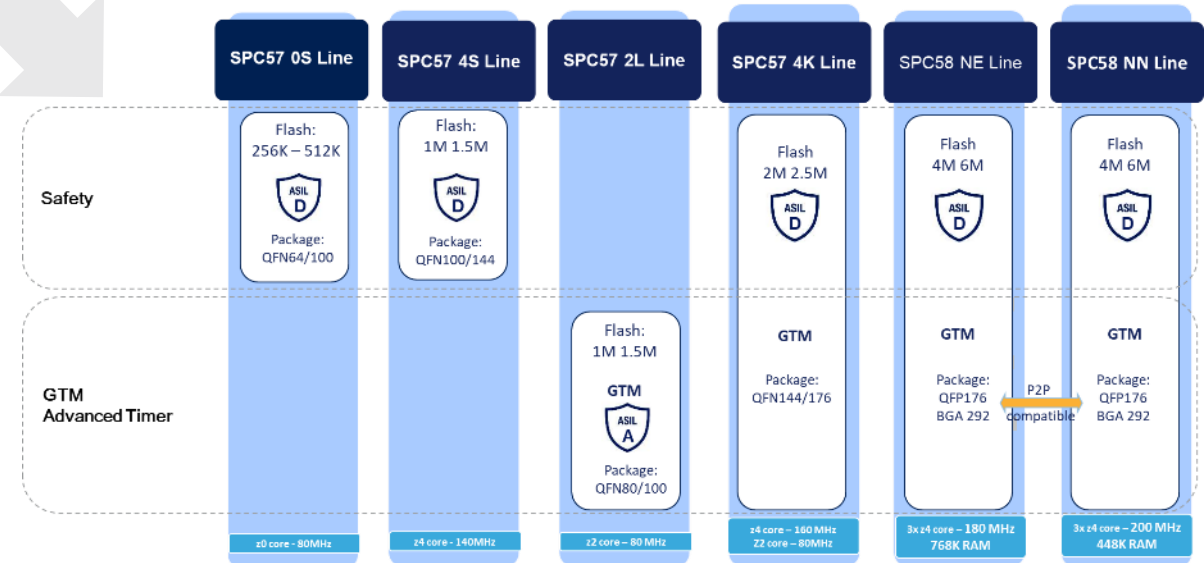


Comprehensive Product Portfolio for General Purpose and New Generation Product Families

SPC5 Chorus Series: Full Scalable & General Purpose



High Performance MCUs: Advanced Safety & Timer

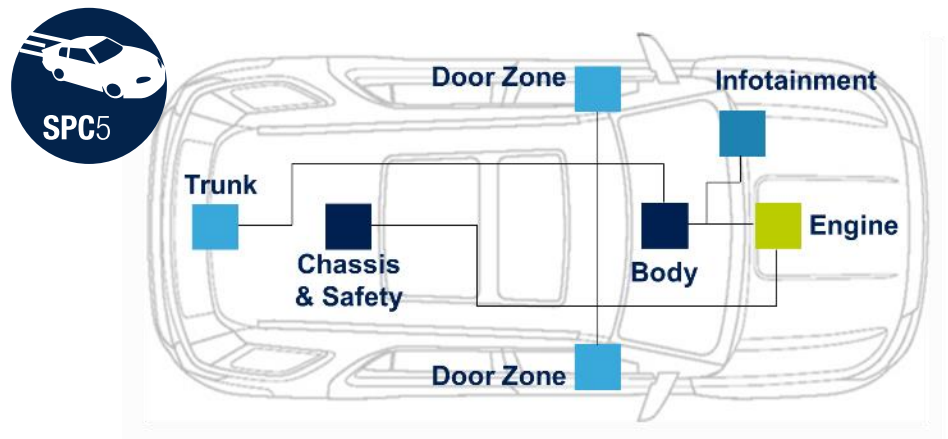




Stellar: driving new architectures

Enabled by ST with FD-SOI 28nm and embedded phase-change memory (PCM)

Distributed Architecture: 9k DMIPS per Car

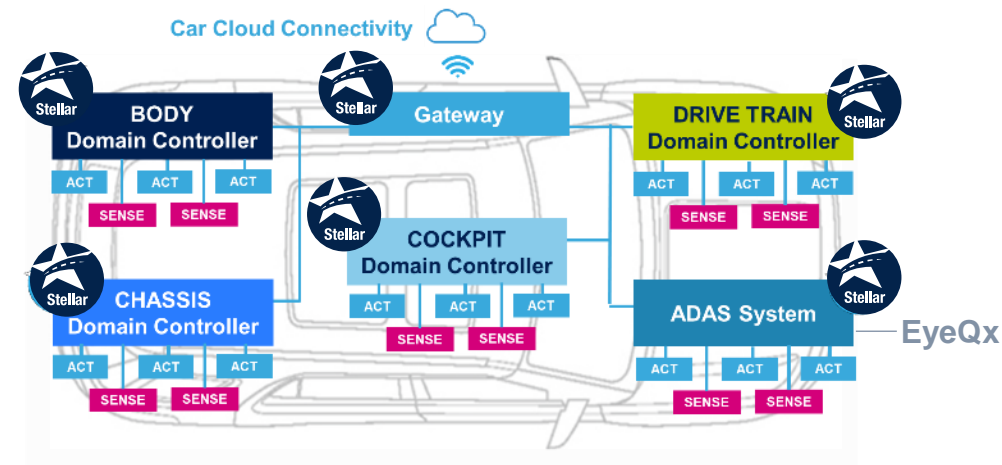


2017

x10

Car
Computational
Power

Integrated Real-time Domain Architecture: 90k DMIPS per Car



202X

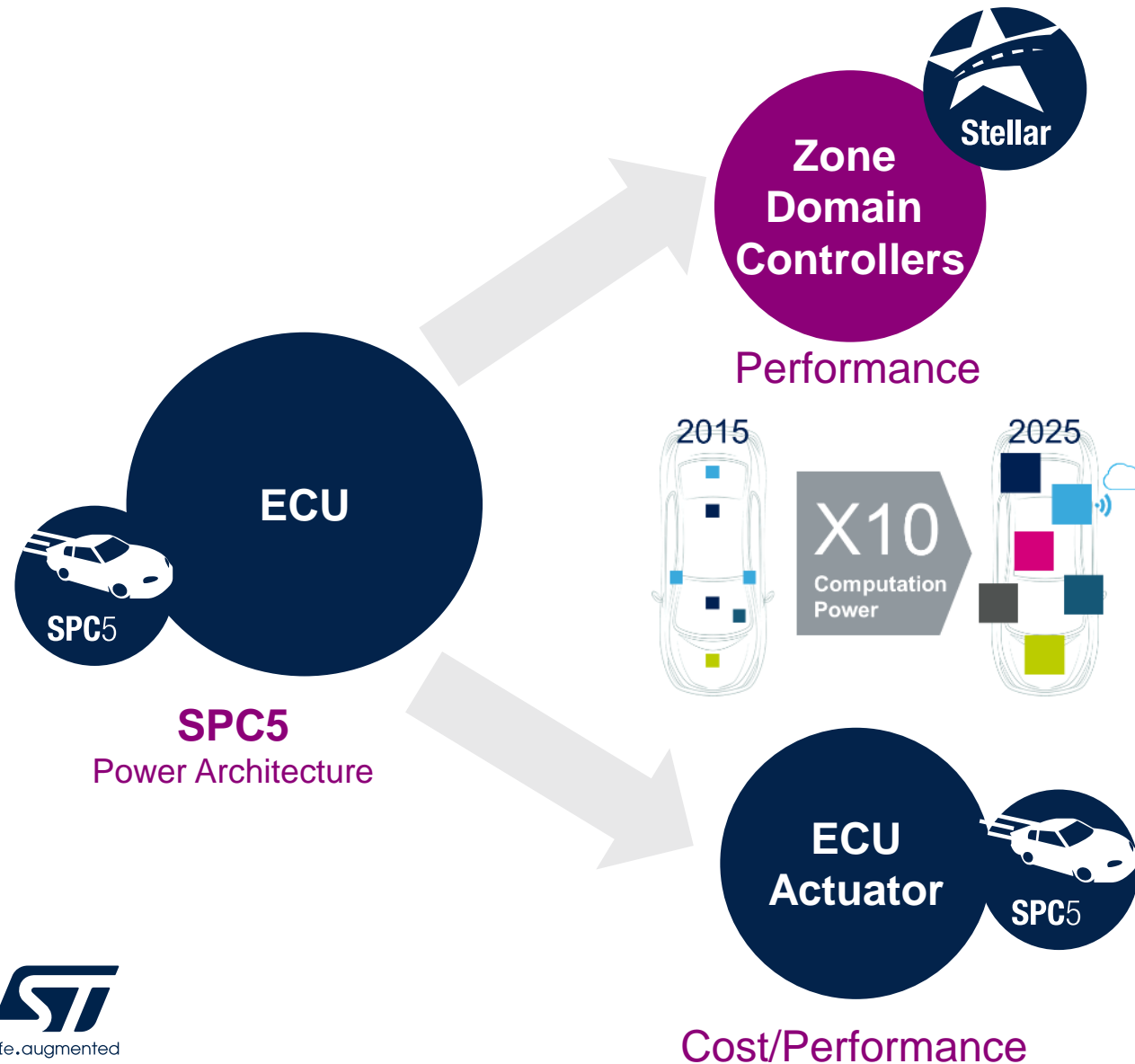
10x more computing power
from 9K DMIPS to 90+ TFLOPS

Defragmentation of main computing units
100 ECUs/Car in 5 main domains

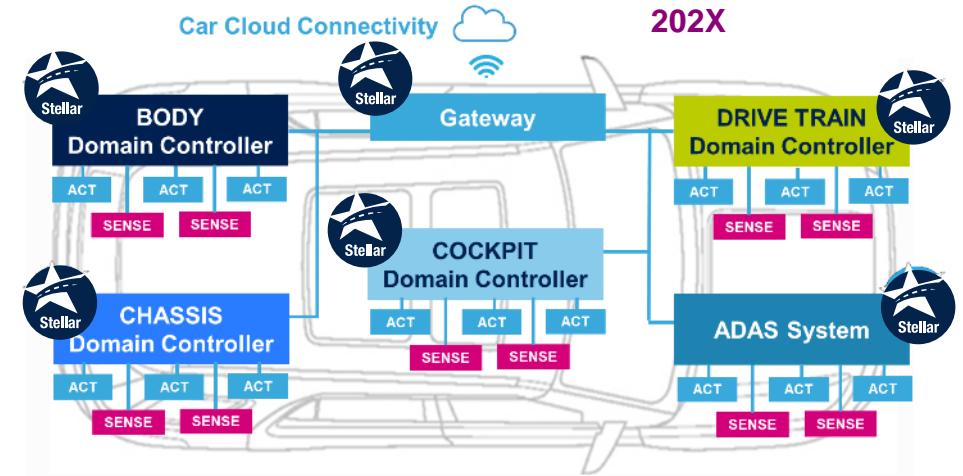
Faster in-vehicle and off-vehicle
data exchange

Enhancing safety and security level

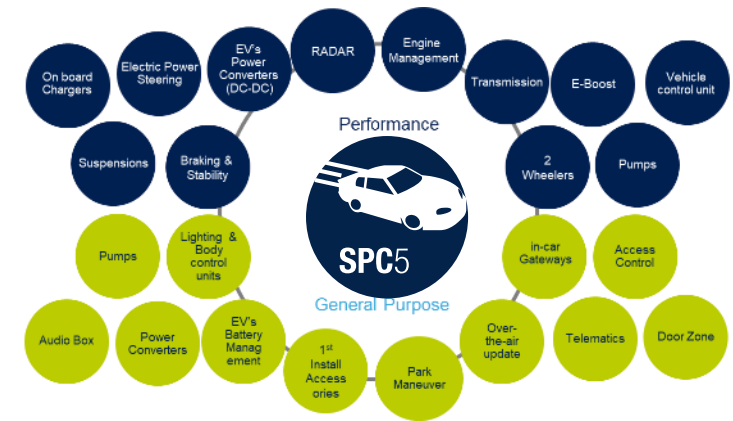
Microcontrollers roadmap evolution



Stellar Arm R52 28nmFDSOI PCM
for High end



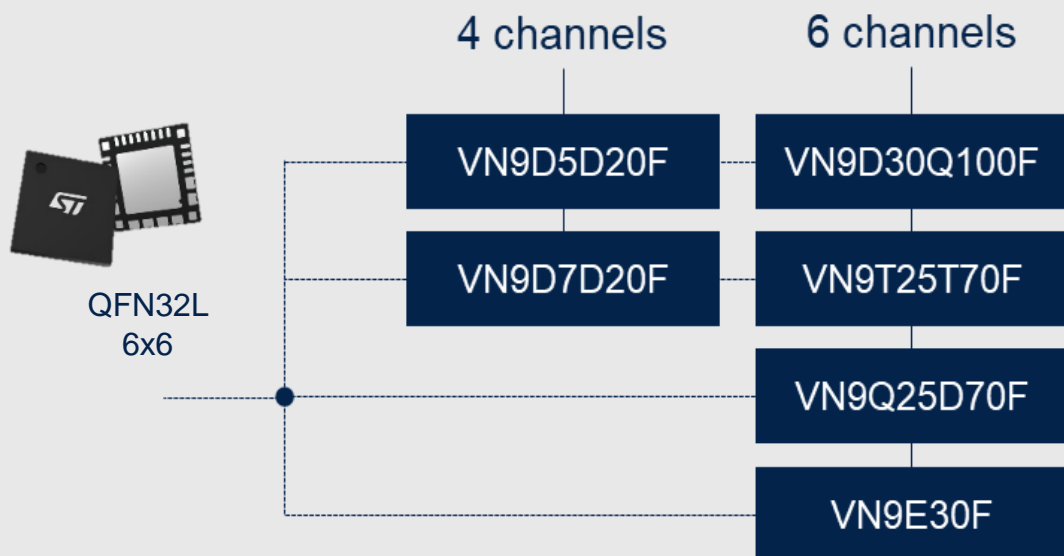
SPC5 Power Architecture Flash NVM for
Single ECUs





M09 SPI high-side drivers the best ever SPI HSDs with advanced digital features

... first family in the world of HSDs with Digital Current Sense



Program Status:

- PQC: Q4.2020...Q4.2022

High Integration to achieve smallest PCB and fewest external component:

- High channel count (up to 6) in small 36mm² footprint (QFN 6x6)
- Low Microcontroller I/O employment, no Microcontroller Analog channels required.

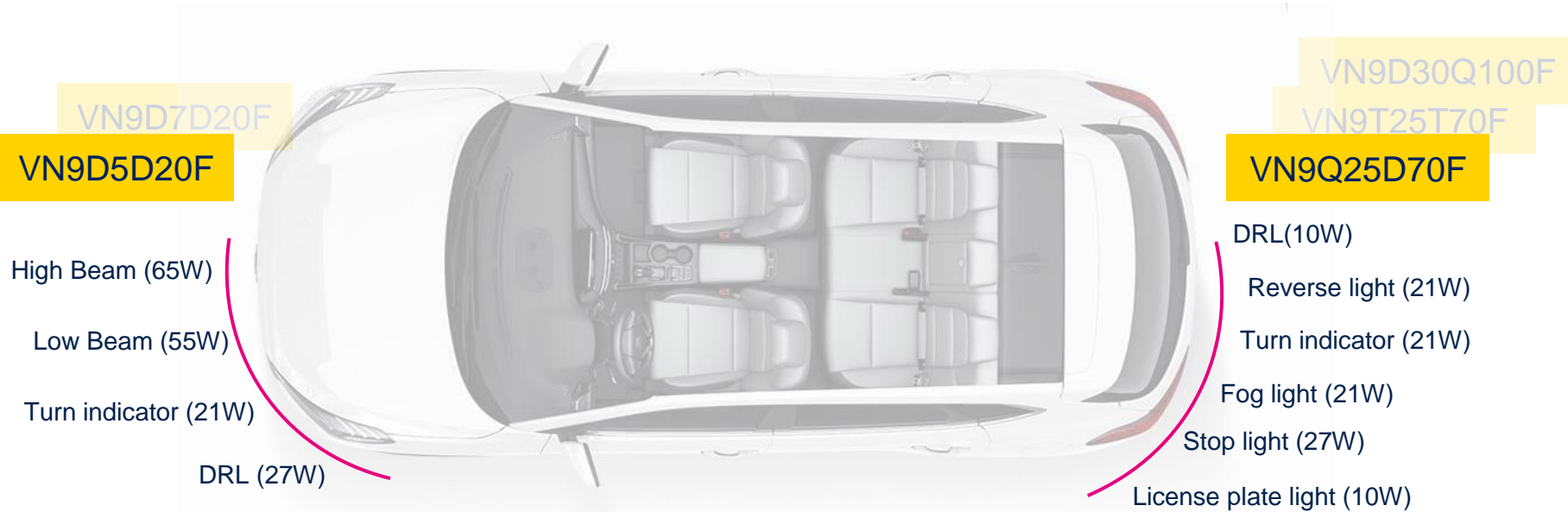
Best Current sense accuracy:

- Less than 7% Digital Current Sense accuracy at Nominal Load, no need of application level calibration.

Easiest Software Design:

- Device integrate PWM engine with fully autonomous and sampled diagnostic.

M0-9 SPI for BCM optimization front and rear corner lights with two devices only



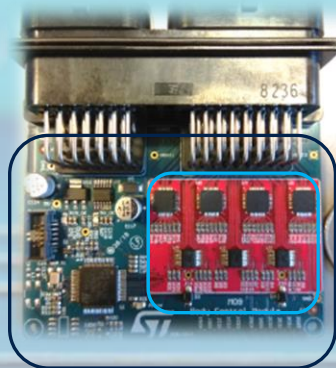
VIpower M0-9 SPI Competitive advantages

-55% PCB Power-Area
vs Parallel Smart Power

-30% external components

Up to **25%** Microcontroller Workload
reduction

-66% Microcontroller I/O and ADC



32 channels PCB driven by seven M0-9 devices only.
Based on a real partitioning from one of the main Tier1

Full PCB: 80x120 mm

Power Area: 30x44 mm

NPP & NSP for Electrification & Digitalization market



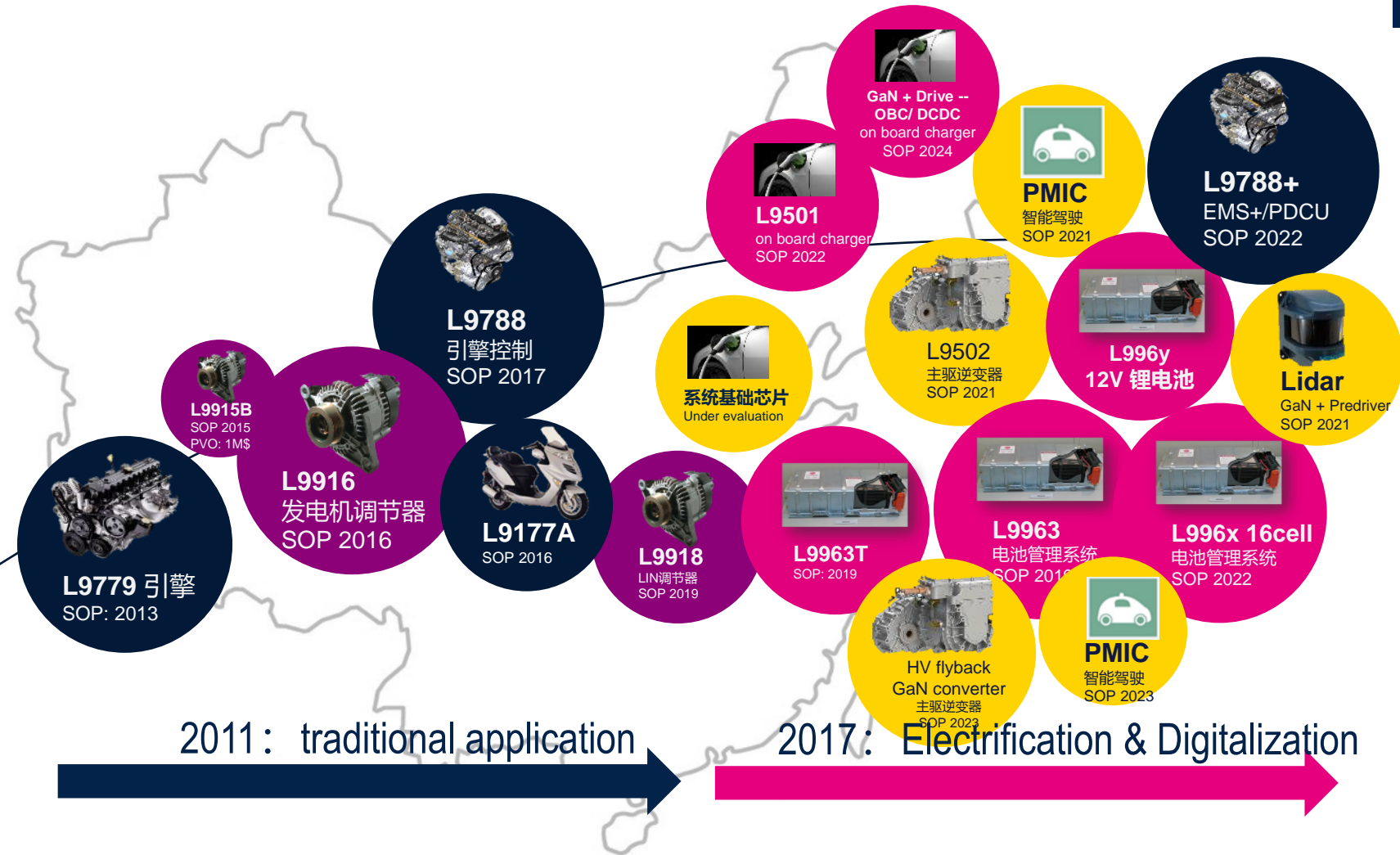
Localized co-development product

Chinese
Customers



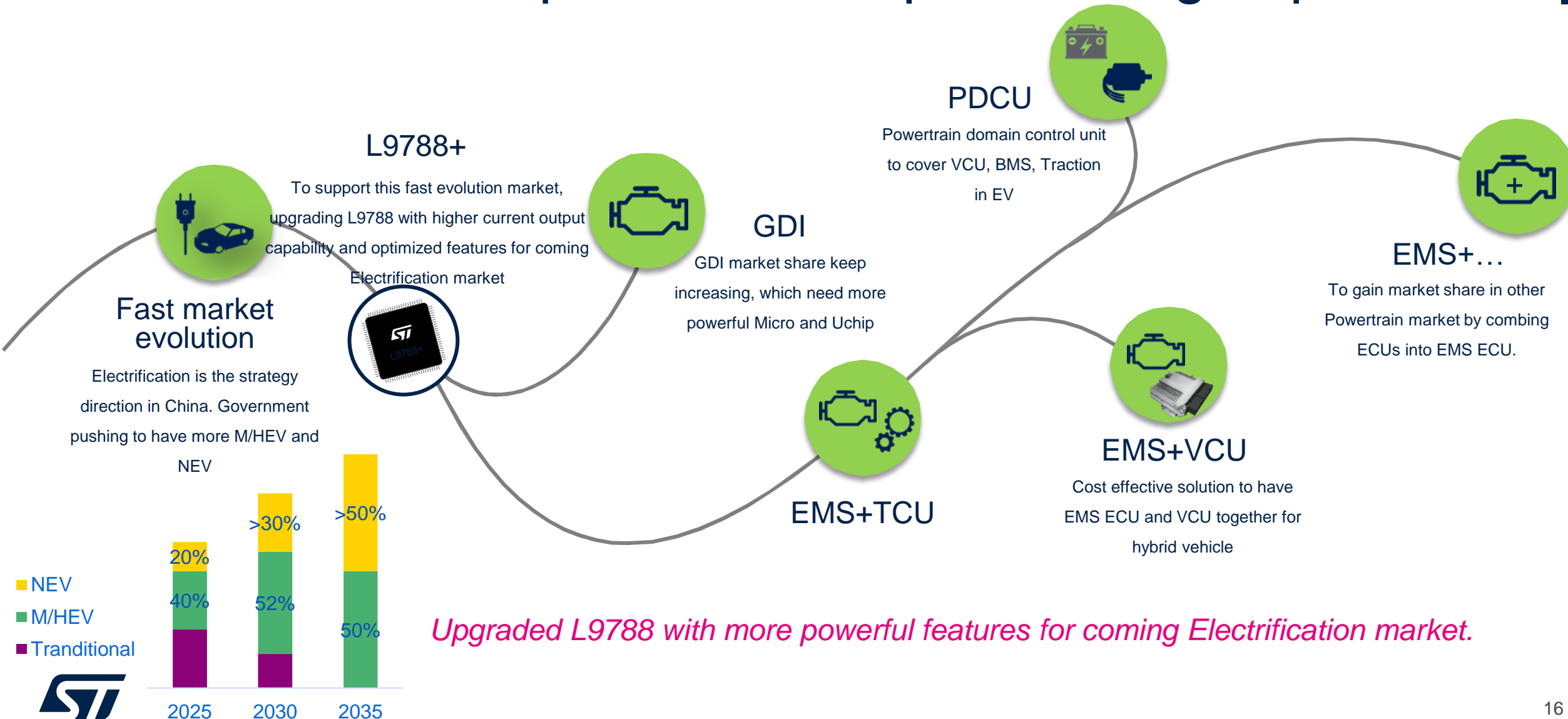
Marketing strategy

Tailored to China Leading
Customer Requirement and
Cross Fertilize to ASIA
and Worldwide market



From division drive to region drive

L9788+ More powerful Uchip for next-gen platforms



2019



整车、动力域控制器

- SPC57, L9788 dual chip solution
- ASIL D
- IDH cooperation

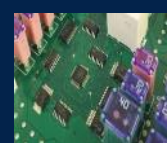
2020



电池管理系统

- $\pm 2\text{mV}$ in whole temp range
- Up to 434 cells
- ASIL-D ready

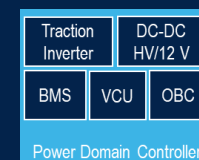
2021



智能电气分配盒

- Efuse
- PowerPC

2022 ~ Later



多合一动力域控制器

- STELLAR E/P, SiC, New SBC, Gate driver
- Real-time Virtualization



在线刷新

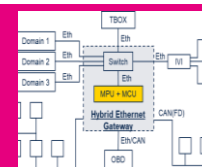
- OTA with 3rd party
- Embedded Hardware Security Module (eHSM)

3KW 充电机



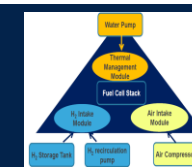
- Single MCU solution for two Power stages
- GB QCT895 compliant

智能网关



- MPU + MCU solution
- Multiple network
- Protocol translation
- Security

燃料电池



- AFE
- Thermal management
- A/C compressor



智能终端

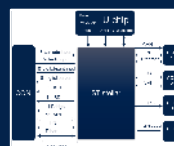
- GB/T32960 compliant
- ASIL-B safety concept
- Scalable CAN-FD interfaces

逆变器



- Total solution with SiC
- ASIL D ready
- Software Resolver

动力域



- VCU + BMS combo
- STELLAR P
- New U chip NPP

智能驾驶电源与外设



- Automotive Processor
- PMIC
- GNSS, Radar, MEMS

2020



电动助力转向

- Target Autonomous Driving through steering redundant function
- ASIL D

OLED



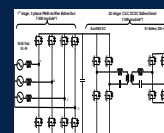
- All in one OLED taillight
- Digitalized, communicational and Personality-oriented

空调压缩机



- Optimized Motor control library
- Efficiency >97% @ 2.0KW

11/22KW 充电机



- 3 phase bidirectional PFC + CLLC DCDC
- STELLAR E1

数字钥匙



- POC project with compliance to CCC 2.0
- SPC582B + ST33-A + ST25

直流变换器

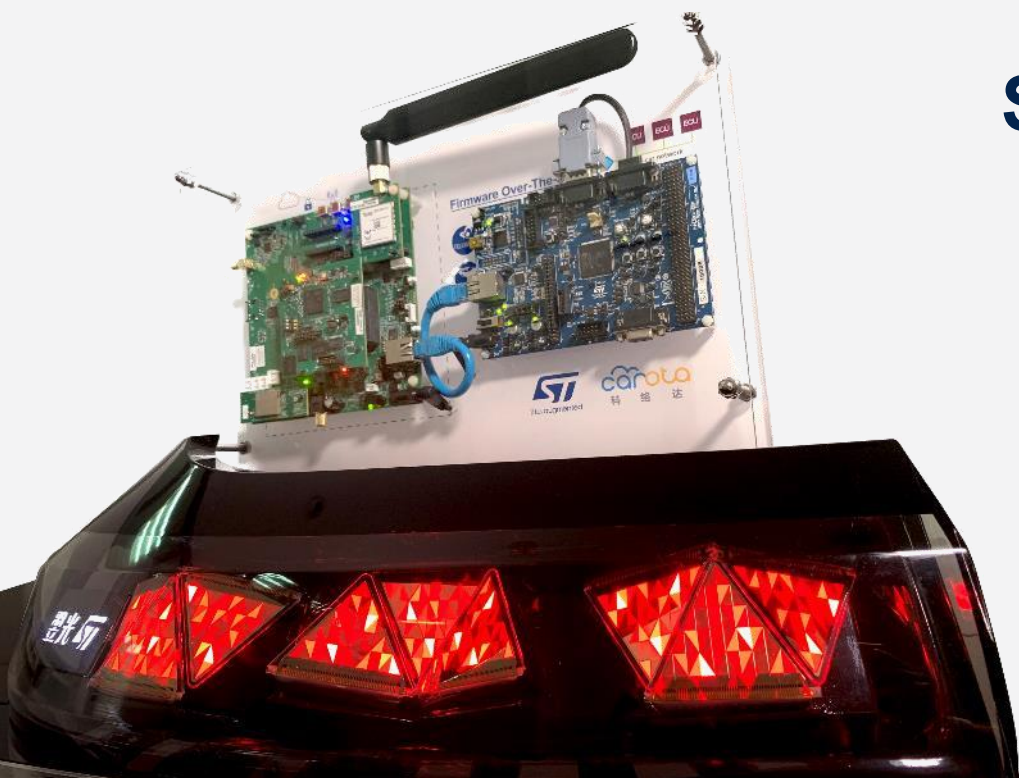


- Full digital Single MCU solution
- High efficiency with SiC MOSFET
- ASIL-C

• 新能源创新中心为您提供**系统解决方案**，包括硬件原理图、Layout设计、底层软件、复杂驱动、功能安全、系统验证报告等。



Digital rear lighting solution



Strategic Partnerships



Leading Over The Air
Service Provider



Leading OLED
Display Supplier

NEV
Competence
Center

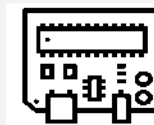


AUTOSAR

BSW on MCU & MPU



*Software utilities
(drivers, flashers)*



System Design Kit



Partners

Top 7 Chinese carmakers are considering adopting an ST Solution



Traction inverter solution

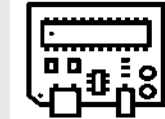
Our Advantages:

- \$ • Software Resolver → **25%** Cost saving
- 🌱 • Gate driver and SiC MOSFET Module Compatibility → **Efficiency**
- 🕒 • Model-Based Design base on MATLAB → **Time to market**
- 🛡️ **ASIL** • System Functional Safety Ready → **Safer**

Our Support & Offer:



**System Functional
Safety**



System Design Kit



Partners



**System Validation
Report**

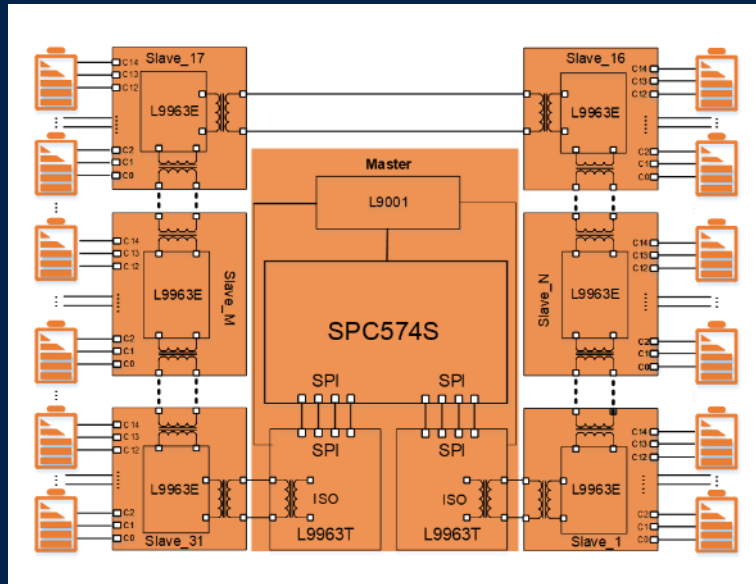




Battery management system

Outline

- Automotive BMS must be able to meet critical features such as voltage, temperature and current monitoring, battery state of charge (SoC) and cell balancing of lithium-ion (Li-ion) batteries.



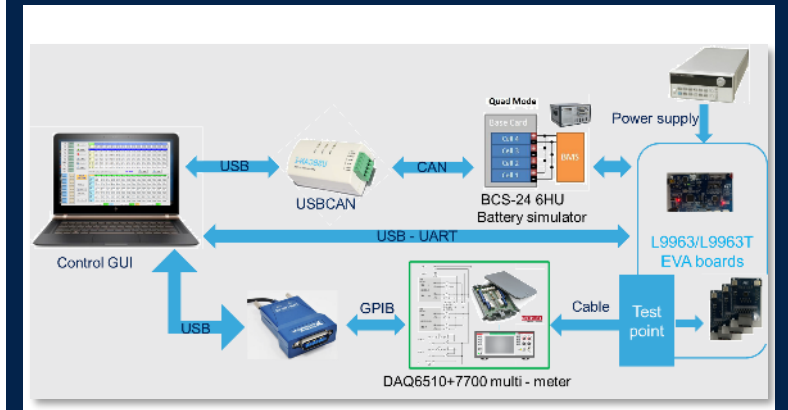
Technical Highlight

- Advanced voltage measurement for up to 434 cells
- High precision with maximum error of $\pm 2\text{mV}$ in whole operating temp range
- Intelligent diagnostics, Function Safety and Robustness
- Easy connection, quick evaluation and low-cost demonstration kit

Function	Product group	ST product
MCU	APG	SPC574S
AFE	APG	L9963E L9963T
Power	APG	L9001

Supporting Package

- Easy connection, quick evaluation and low-cost demonstration kit
- Evaluation GUI
- Reference code on SPC5Studio
- Application notes
- Databrief / Datasheet
- Safety manual
- FMEDA / DFA



Successful story with NEV Competence Center system solution development

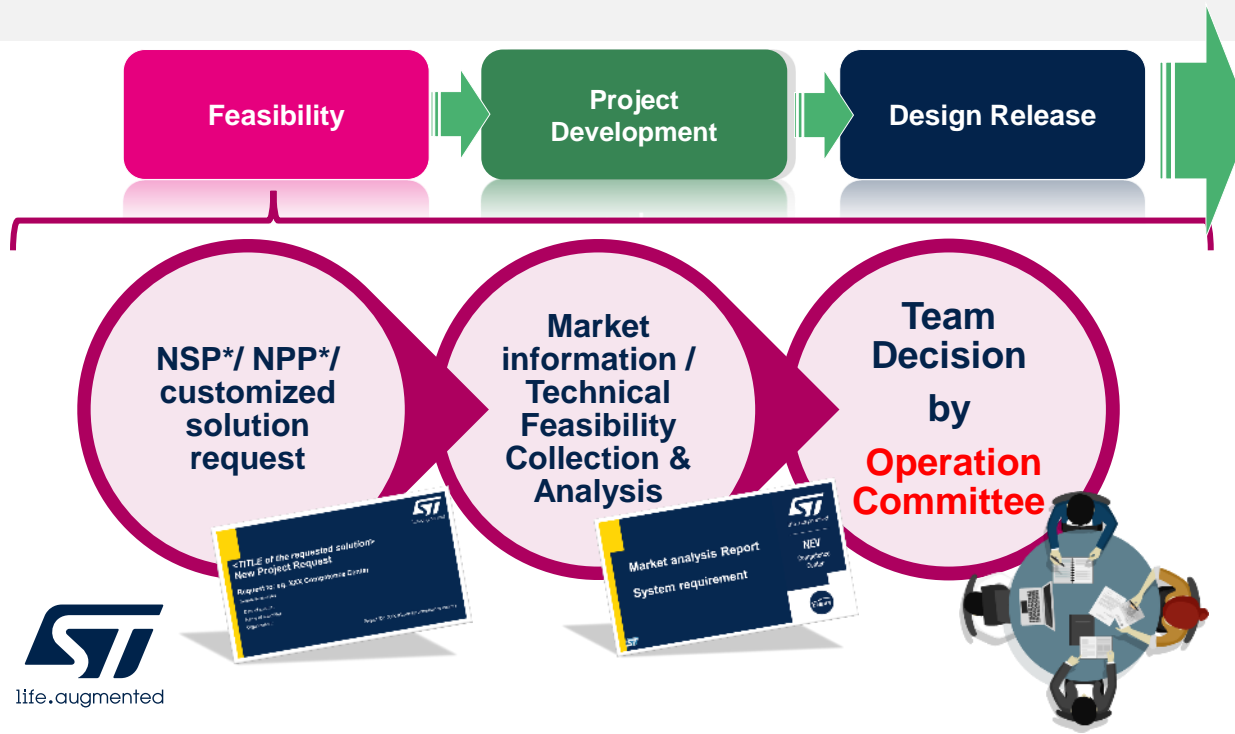
NEV Competence Center Vision

Leverage

- ST wide & strong **Product Portfolio**
- Strong **Software & System** knowhow in ST GCSA
- ST system solution & support

Key Objective

- Improving AP customer project **Time to Market**



- ✓ User Friendly Design Kit
- ✓ Provide Support & Consultation Throughout Customer Project Development Cycle

Business Opportunity Engagement

- Provide reference design kit, document and test report
- Competitor solution / component benchmark
- Application scenario evaluation in system
- Training & workshop

Design IN

- Low level driver / CDD development
- MCAL customization
- Hardware design & debug
- Application specific algorithms development
- System software development
- System safety analyze

DV & PV

- EMC performance optimization
- Joint bench test
- Data log analyze
- System safety assessment consultant

To Ensure SOP on time



Kit Solution

**Time to
Market**

**Quality &
Safety**

**Easy to
Use**

- **Time to market**

Develop & supporting complete system solution helping customer to shorten development cycle-time.

- **Quality & Safety**

Support system level functional safety, complex driver compliant to AUTOSAR.

- **Customization**

Support customized Solution and Product development.

- **Easy to Use**

Provide product & solution training enhancing IDH and distribution system technical knowhow & competency

Thank you

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